

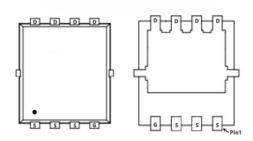
68V N-Channel Enhancement Mode MOSFET

Description

The SX80N07NF uses advanced trench technology to provide excellent RDS(ON), low gate charge and operation with Hight EAS. This device is suitable for use as a Battery protectionor in other Switching application.

PDFN5*6-8L





General Features

V_{DS} = 68V I_D =80A

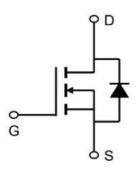
 $R_{DS(ON)} < 9.0 m\Omega$ @ $V_{GS}=10V$

Application

Battery protection

Load switch

Uninterruptible power supply



Absolute Maximum Ratings (Tc=25°C unless otherwise noted)

| Symbol | Parameter | Rating | Units | |
|--------------------|---|--|------------|--|
| VDS | Drain-Source Voltage | 68 | V | |
| VGS | Gate-Source Voltage | e Voltage ±20 | | |
| l o@Tc=25℃ | Continuous Drain Current, V _{GS} @ 10V ¹ 80 | | Α | |
| b@Tc=100°C | Continuous Drain Current, V _{GS} @ 10V ¹ | Drain Current, Ves @ 10V ¹ 52 | | |
| IDM | Pulsed Drain Current ² | 320 | Α | |
| EAS | Single Pulse Avalanche Energy ³ | 110 | mJ | |
| IAS | Avalanche Current | 22 | Α | |
| P @Tc=25 ℃ | Total Power Dissipation ⁴ | 103 | W | |
| TSTG | Storage Temperature Range | -55 to 150 | $^{\circ}$ | |
| TJ | Operating Junction Temperature Range | -55 to 150 | $^{\circ}$ | |
| R⊕JA | Thermal Resistance Junction-ambient ¹ | 63 | °C/W | |
| ReJC | Thermal Resistance Junction-Case ¹ | 1.46 | °C/W | |





Electrical Characteristics (T_J=25℃, unless otherwise noted)

| Symbol | Parameter | Conditions | Min. | Тур. | Max. | Unit |
|----------------------|--|--|------|-------|------|------|
| BVDSS | Drain-Source Breakdown Voltage | Vgs=0V , Ip=250uA | 68 | 72 | | V |
| ∆BVDSS/∆TJ | BVDSS Temperature Coefficient | Reference to 25℃, I _D =1mA | | 0.023 | | V/°C |
| RDS(ON) | Static Drain-Source On-Resistance ² | Vgs=10V , Ip=10A | | 7.5 | 9.0 | mΩ |
| VGS(th) | Gate Threshold Voltage | Vgs=Vps , Ip =250uA | 2.0 | 3.0 | 4.0 | V |
| $\triangle V$ GS(th) | V _{GS(th)} Temperature Coefficient | VGS-VDS , ID -230UA | | -4.2 | | mV/℃ |
| IDSS | Drain-Source Leakage Current | Vbs=68V , Vgs=0V , TJ=25℃ | | | 1 | uA |
| | Dialii-Godice Leakage Guitelii | V _D s=68V , V _G s=0V , T _J =55℃ | | | 5 | uA |
| IGSS | Gate-Source Leakage Current | Vgs=±20V , Vps=0V | | | ±100 | nA |
| Q_g | Total Gate Charge (4.5V) | | | 35 | | nC |
| Qgs | Gate-Source Charge | VDS =30V, ID =30A, VGS =10V | | 11 | | |
| Qgd | Gate-Drain Charge | | | 9 | | |
| Td(on) | Turn-On Delay Time | | | 15 | | ns |
| Tr | Rise Time | VDS =30V,ID =30A, | | 90 | | |
| Td(off) | Turn-Off Delay Time | RGEN =3 Ω , V GS =10V | | 45 | | |
| Tf | Fall Time | | | 30 | | |
| Ciss | Input Capacitance | | | 4060 | | |
| Coss | Output Capacitance | V _{DS} =15V , V _{GS} =0V , f=1MHz | | 267 | | pF |
| Crss | Reverse Transfer Capacitance | | | 250 | | |
| IS | Continuous Source Current ^{1,5} | | | | 80 | Α |
| ISM | Pulsed Source Current ^{2,5} | V _G =V _D =0V , Force Current | | | 320 | Α |
| VSD | Diode Forward Voltage ² | V GS =0V, I S =80A | | | 1.2 | V |
| trr | Reverse Recovery Time | T J =25℃ | | 78 | | nS |
| Qrr | Reverse Recovery Charge | I F =20A,dI/dt=100A/μs | | 51 | | nC |

Note:

- 1. The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper.
- $2\sqrt{100}$ The data tested by pulsed , pulse width .The EAS data shows Max. rating .
- 3 \setminus The test cond \leq 300us duty cycle \leq 2%, duty cycle ition is TJ =25 $^{\circ}$ C, VDD =35V, VG =10V, R G =25 Ω , L=0.5mH, IAS =21A

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- 4. The power dissipation is limited by 175 $\!\!\!\!^{\circ}\!\!\!\!^{\circ}$ junction temperature
- 5. The data is theoretically the same as ID and IDM, in real applications, should be limited by total power dissipation.

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Typical Characteristics

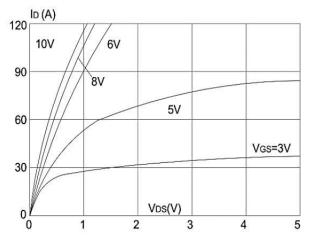


Figure1: Output Characteristics

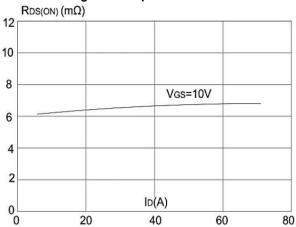


Figure 3:On-resistance vs. Drain Current

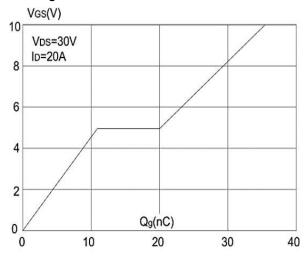


Figure 5: Gate Charge Characteristics

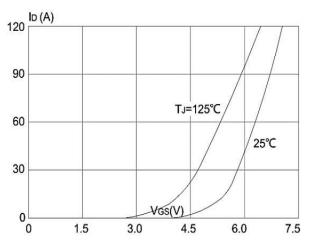


Figure 2: Typical Transfer Characteristics

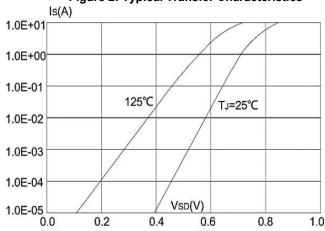


Figure 4: Body Diode Characteristics

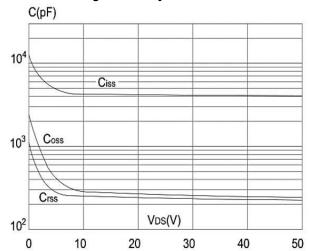


Figure 6: Capacitance Characteristics



Typical Characteristics

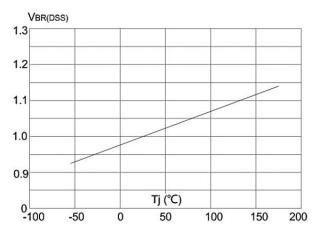


Figure 7: Normalized Breakdown Voltage vs Junction Temperature

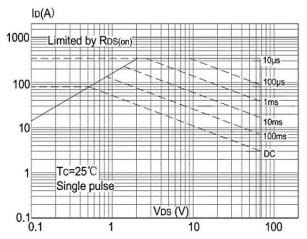


Figure 9: Maximum Safe Operating Area

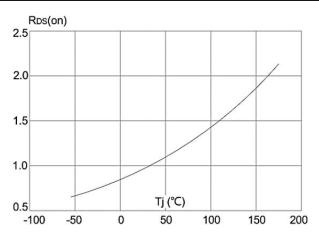


Figure 8: Normalized on Resistance vs.

Junction Temperature

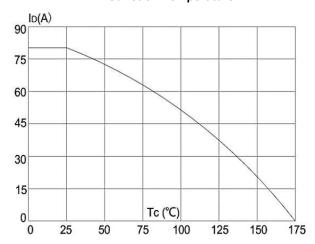


Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature

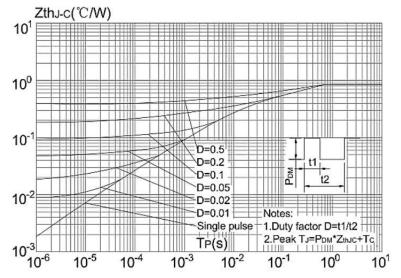
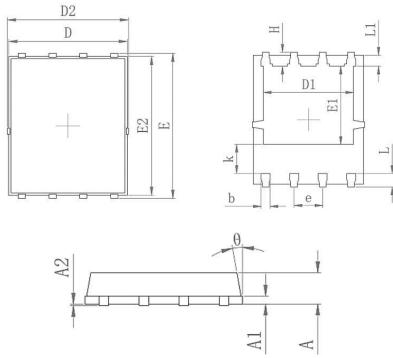


Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambien

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Package Mechanical Data-PDFN5X6-8L-XZT Single



| | Common | | | |
|--------|--------|-------|--|--|
| Symbol | mm | | | |
| | Mim | Max | | |
| A | 0.90 | 1.10 | | |
| A1 | 0.254 | REF | | |
| A2 | 0-0.05 | | | |
| D | 4.824 | 4.976 | | |
| D1 | 3.910 | 4.110 | | |
| D2 | 4.944 | 5.076 | | |
| E | 5.924 | 6.076 | | |
| E1 | 3.375 | 3.575 | | |
| E2 | 5.674 | 5.826 | | |
| b | 0.350 | 0.450 | | |
| е | 1.270 | | | |
| L | 0.534 | 0.686 | | |
| L1 | 0.424 | 0.576 | | |
| К | 1.190 | 1.390 | | |
| Н | 0.549 | 0.701 | | |
| Ф | 8° | 12° | | |

Package Marking and Ordering Information

| Product ID | Pack | Marking | Qty(PCS) |
|------------|------------|---------|----------|
| TAPING | PDFN5X6-8L | | 5000 |

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